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LIST OF DOCUMENTS CITED BY APPLICANT
(Use several sheets if necessary)

APPLICANT

Xian J. Ning

FILING DATE
May 14, 2001

GROUP
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11033 U.S. PTO
09/854760
05/14/01

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AL							
	AM							
	AN							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

LV	AO	Chi-Tzung Wang, et al., Pad Wear Analysis in CMP; 1999 VMIC Conference; 1999 IMIC 109/99/0267(c)					
LV	AP	Srin Raghavan, et al., Electrochemical Behavior of Copper and Tantalum in Silica Slurries Containing Hydroxylamine, 1999 VMIC Conference; 1999 IMIC 109/99/0619(c)					
LV	AQ	Rajeev Bajaj, et al., Manufacturability Considerations and Approaches for Development of a Copper CMP Process; 1999 VMIC Conference; 1999 IMIC 109/99/0144(c)					

DATE COMPILED: 12/4/2003

EXAMINER: LAN VINH

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